

## ACE2302CBM+H-VB Datasheet N-Channel 20 V (D-S) MOSFET

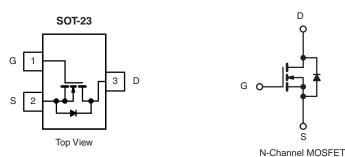
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$\mathbf{R}_{DS(on)}$ (Ω) $\mathbf{I}_{D}$ (A) <sup>e</sup>		Q <sub>g</sub> (Typ.)			
	0.022 at V <sub>GS</sub> = 4.5 V	6 <sup>a</sup>				
20	0.028 at V <sub>GS</sub> = 2.5 V	6 <sup>a</sup>	8.8 nC			
	0.039 at V <sub>GS</sub> = 1.8 V	5.6				

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21
  Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

- DC/DC Converters
- Load Switch for Portable Applications



ABSOLUTE MAXIMUM RATIN	$H_{A} = 25  C,$				
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 12		
	T <sub>C</sub> = 25 °C		6 <sup>a</sup>		
Continuous Drain Current ( $T_1 = 150 \ ^{\circ}C$ )	T <sub>C</sub> = 70 °C		5.1		
Continuous Drain Current $(1) = 150^{\circ}$ C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	5 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		4 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	20		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	L.	1.75		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	IS	1.04 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		2.1		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	PD	1.3	w	
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	гD	1.25 <sup>b, c</sup>	~~~	
	T <sub>A</sub> = 70 °C		0.8 <sup>b, c</sup>		
Operating Junction and Storage Temperature	Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	
Soldering Recommendations (Peak Tempera	ature)	Ŭ	260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	80	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	40	60	0/11	

Notes:

a. Package limited

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 125  $^{\circ}\text{C/W}.$ 

e. Based on T\_C = 25 °C.



FREE

<b>SPECIFICATIONS</b> $T_J = 25 \text{ °C}$ , u	inless othe	rwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A	20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		25		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}\!/T_J$			- 2.6		1110/ 0	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	0.45		1.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 8 \text{ V}$			± 100	nA	
	lass	$V_{DS} = 20 V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 70 °C			10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS}{\leq}5$ V, $V_{GS}{=}4.5$ V	20			A	
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$		0.022			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 4.7 \text{ A}$		0.028		Ω	
		$V_{GS} = 1.8 \text{ V}, \text{ I}_{D} = 4.3 \text{ A}$		0.039			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$		24		S	
Dynamic <sup>b</sup>					•		
Input Capacitance	C <sub>iss</sub>			865			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		105		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			55			
Total Oata Obarra	0	$V_{DS} = 10 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 5.0 \text{ A}$		12	18		
Total Gate Charge	Qg			8.8	14		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 5.0 A		1.1		nC	
Gate-Drain Charge	Q <sub>gd</sub>			0.7			
Gate Resistance	Rg	f = 1 MHz	0.5	2.4	4.8	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			8	16		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 2.2 $\Omega$		17	26	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong \text{4}$ A, $\text{V}_\text{GEN}$ = 4.5 V, $\text{R}_\text{g}$ = 1 $\Omega$		31	47		
Fall Time	t <sub>f</sub>			8	16	ns	
Turn-On Delay Time	t <sub>d(on)</sub>			5	10		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 2.2 $\Omega$		13	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 4 \text{ A}, V_{GEN} = 5 \text{ V}, R_g = 1 \Omega$		21	32		
Fall Time	t <sub>f</sub>			6	12	-	
Drain-Source Body Diode Characteristic	s		4	•	•		
Continuous Source-Drain Diode Current	ا <sub>S</sub>	T <sub>C</sub> = 25 °C			1.75	۸	
Pulse Diode Forward Current	I <sub>SM</sub>				20	A	
Body Diode Voltage	V <sub>SD</sub>	$I_{S} = 4 A, V_{GS} = 0 V$		0.75	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			12	20	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 4 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		5	10	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$r_{\rm F} = 7.7$ , $u_0 u_1 = 100 R/\mu_0$ , $r_{\rm J} = 20 0$		7		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			5			

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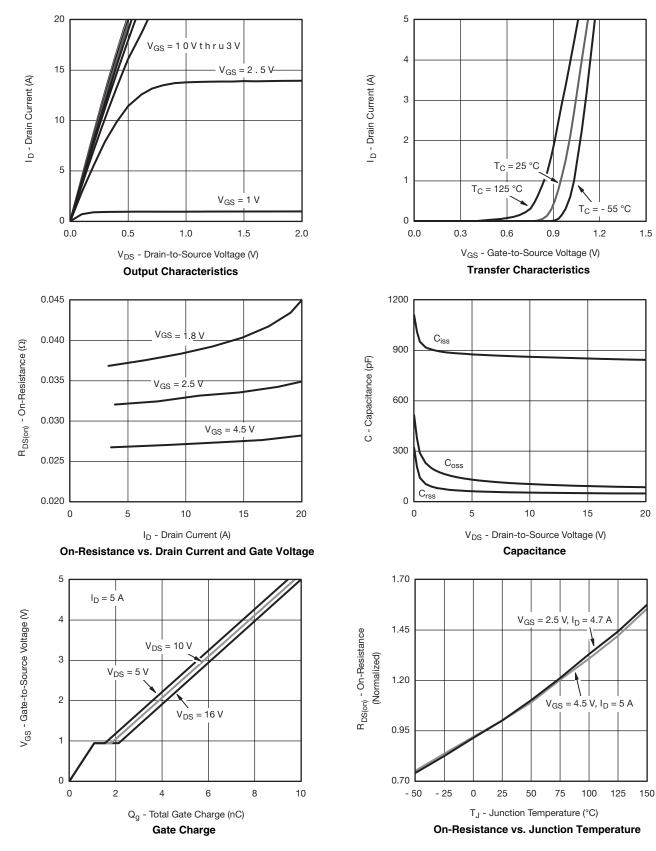
Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





 $I_D = 5 A$ 

T<sub>J</sub> = 125 °C

 $T_J = 25 \ ^{\circ}C$ 

6

10

100

1

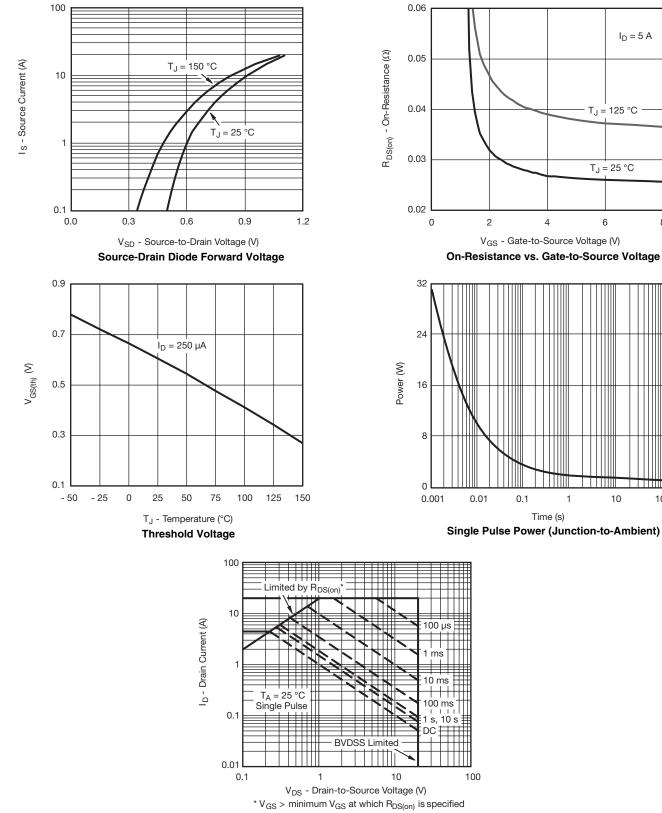
Time (s)

8

4

0.1

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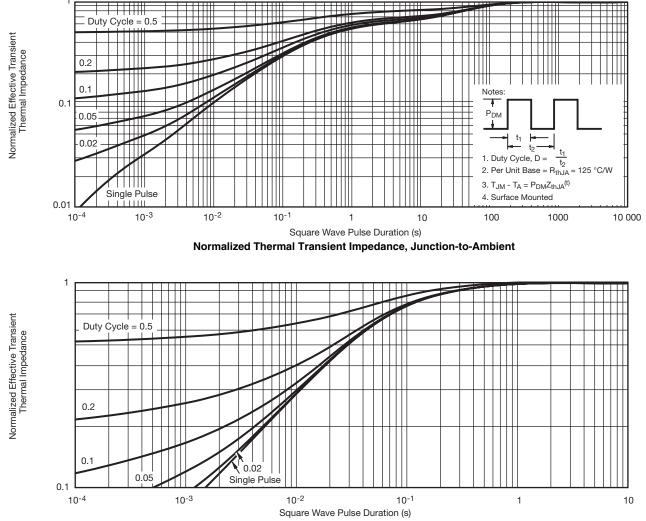
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\* The power dissipation  $P_D$  is based on  $T_{J(max.)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

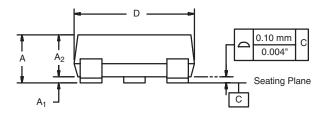


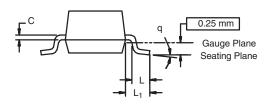




### SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	IETERS	INCHES			
	Min	Мах	Min	Max		
Α	0.89	1.12	0.035	0.044		
A <sub>1</sub>	0.01	0.10	0.0004	0.004		
A <sub>2</sub>	0.88	1.02	0.0346	0.040		
b	0.35	0.50	0.014	0.020		
С	0.085	0.18	0.003	0.007		
D	2.80	3.04	0.110	0.120		
E	2.10	2.64	0.083	0.104		
E <sub>1</sub>	1.20	1.40	0.047	0.055		
е	0.95 BSC		0.0374 Ref			
e <sub>1</sub>	1.90	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024		
L <sub>1</sub>	0.64 Ref		0.025 Ref			
S	0.50 Ref		0.020 Ref			
q	3°	8°	3°	8°		
ECN: S-03946-Rev. K, 09-Jul-01 DWG: 5479						

## ACE2302CBM+H-VB



#### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)



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